

General Description

The MAX3314E is a ±5V-powered EIA/TIA-232-compatible interface. It has one transmitter and one receiver in a flow-through architecture. The transmitter output and the receiver input are protected to ±15kV using IEC 1000-4-2 Air-Gap Discharge, ±8kV using IEC 1000-4-2 Contact Discharge, and ±15kV using the Human Body Model.

The transmitter has a low-dropout output stage providing minimum RS-232-compatible ±3.7V output levels while driving $3k\Omega$ and 1000pF at 460kbps. Both +5Vand -5V must be supplied externally.

The MAX3314E has a SHDN function that reduces supply current to 1µA. The transmitter is disabled and put into tristate while the receiver remains active.

The MAX3314E is available in 8-pin µMAX and SO packages.

Applications

Digital Cameras

PDA

GPS

POS

Telecommunications

Handy-Terminals

Set-Top Boxes

Features

- ♦ ESD Protection for RS-232 I/O Pins ±15kV—Human Body Model ±8kV—IEC 1000-4-2 Contact Discharge ±15kV—IEC 1000-4-2 Air-Gap Discharge
- ♦ 1µA Low-Power Shutdown with Receiver Active
- ♦ 30µA Operating Supply Current
- ♦ 460kbps Guaranteed Data Rate
- ♦ 8-Pin µMAX Package
- ♦ ±3.7V RS-232-Compatible Levels

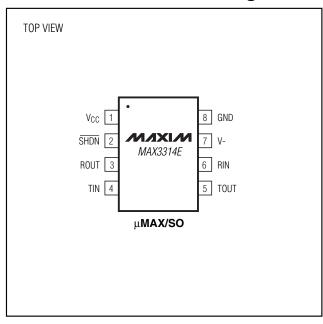
Ordering Information

PART	TEMP. RANGE	PIN-PACKAGE
MAX3314ECUA	0°C to +70°C	8 μMAX
MAX3314ECSA	0°C to +70°C	8 SO
MAX3314EEUA	-40°C to +85°C	8 μMAX
MAX3314EESA	-40°C to +85°C	8 SO

Typical Operating Circuit

<u>+</u> CBYPASS 0.1μF ′ V_{CC} SHDN MIXIM MAX3314E TOUT 8 CAPACITORS MAY BE POLARIZED OR NONPOLARIZED.

Pin Configuration



MIXIM

Maxim Integrated Products 1

ABSOLUTE MAXIMUM RATINGS

V _{CC} to GND	0.3V to +6V
V- to GND	+0.3V to -6V
Input Voltages	
TIN, SHON to GND	0.3V to +6V
RIN to GND	±25V
Output Voltages	
TOUT to GND	±13.2V
ROUT	0.3V to (V _{CC} + 0.3V)
Short-Circuit Duration	
TOUT to GND	Continuous

Continuous Power Dissipation 8-Pin µMAX (derate 4.1mW/°C above +70 8-Pin SO (derate 5.88mW/°C above +70	
Operating Temperature Ranges	,
MAX3314EC_A	0°C to +70°C
MAX3314EE_A	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(V_{CC} = +5V, V- = -5V, T_A = T_{MIN} to T_{MAX}. Typical values are at T_A = +25°C.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DC CHARACTERISTICS	•		•			•
Positive Supply Operating Range	Vcc		4.75	5	5.25	V
Negative Supply Operating Range	V-		-4.75	-5	-5.25	V
Positive Supply Current		SHDN = V _{CC} , no load		30	100	μΑ
Negative Supply Current		SHDN = V _{CC} , no load		15	30	μΑ
Shutdown Supply Current		SHDN = GND		1	10	μΑ
LOGIC INPUTS (TIN, SHDN)	•					
Input Logic Threshold Low	V _{IL}		0.8			V
Input Logic Threshold High	VIH				2.4	V
Transmitter Input Hysteresis				0.5		V
Input Leakage Current				±0.01		μΑ
RECEIVER OUTPUT	•					
Output Voltage Low	V _{OL}	I _{OUT} = 1.6mA			0.4	V
Output Voltage High	VoH	I _{OUT} = -1.0mA	V _C C - 0.3	V _C C - 0.1		V
RECEIVER INPUT			1			ı
Input Threshold Low	V _{IL}		0.8			V
Input Threshold High	VIH				2.4	V
Input Hysteresis				0.5		V
Input Resistance				5		kΩ
TRANSMITTER OUTPUT						
Output Voltage Swing		Transmitter output loaded with $3k\Omega$ to ground	±3.7			V
Output Resistance (Note 1)		V _{CC} = V- = 0, transmitter output = ±2V	300			Ω
Output Short-Circuit Current					±60	mA
Output Leakage Current		V _{OUT} = ±12V, transmitter disabled			25	μΑ
ESD PROTECTION (Transmitter	Output, Rece	iver Input)				
		Human Body Model		±15		
ESD-Protection Voltage		IEC 1000-4-2 Air-Gap Discharge		±15		kV
		IEC 1000-4-2 Contact Discharge		±8		

TIMING CHARACTERISTICS

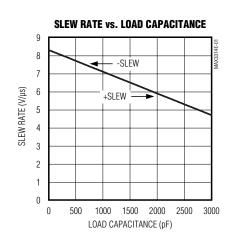
(V_{CC} = +5V, V- = -5V, T_A = T_{MIN} to T_{MAX} . Typical values are at T_A = +25°C.)

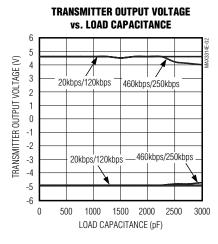
PARAMETER	SYMBOL CONDITIONS		MIN	TYP	MAX	UNITS	
Maximum Data Rate	kimum Data Rate $ \begin{array}{c} R_L = 3k\Omega, \ C_L = 1000 pF, \ transmitter \\ switching \end{array} $		460			kbps	
Receiver Propagation Delay	T _{PLH}	Receiver input to receiver output, C _L = 150pF		0.15			
	T _{PHL}	Receiver input to receiver output, C _L = 150pF		0.15		μs	
Transmitter Skew				100		ns	
Receiver Skew				50		ns	
Transition Region Slew Rate		$R_L = 3k\Omega$ to $7k\Omega$, $C_L = 150pF$ to 1000pF, measured from +3V to -3V or -3V to +3V		8		V/µs	

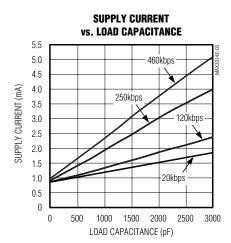
Note 1: Not tested, guaranteed by design.

_Typical Operating Characteristics

 $(V_{CC} = +5V, V_{-} = -5V, 250 \text{kbps} \text{ data rate, transmitter loaded with } 3k\Omega \text{ and } C_L, T_A = +25^{\circ}C, \text{ unless otherwise noted.})$







Pin Description

PIN	PIN NAME FUNCTION		
1	V _{CC}	+5V ±5% External Power Supply. Decouple with a 0.1μF capacitor to ground.	
2	SHDN	Shutdown, Active low (0 = off, 1 = on).	
3	ROUT	TTL/CMOS Receiver Output	
4	TIN	L/CMOS Transmitter Input	
5	TOUT	-232-Compatible Transmitter Output	
6	RIN	S-232-Compatible Receiver Input	
7	V-	-5V ±5% External Power Supply. Decouple with a 0.1μF capacitor to ground.	
8	GND	Ground	

Detailed Description

RS-232-Compatible Drivers

The transmitter is an inverting level translator that converts CMOS-logic levels to $\pm 3.7 V$ EIA/TIA-232-compatible levels. It guarantees data rates up to 460kbps with worst-case loads of $3 k\Omega$ in parallel with 1000pF. When SHDN is driven low, the transmitter is disabled and put into tristate. The transmitter input does not have a pull-up resistor. Connect to ground if unused.

RS-232-Compatible Receivers

The MAX3314E's receiver converts RS-232 signals to CMOS-logic output levels. The receiver is rated to receive signals to ±25V. It will remain active during shutdown mode.

MAX3314E Shutdown Mode

In shutdown mode, the transmitter output is put into high impedance (Table 1). This reduces supply current to $1\mu A$. The time required to exit shutdown is less than $2.5\mu s$.

_Applications Information

Capacitor Selection

The capacitor type used is not critical for proper operation; either polarized or nonpolarized capacitors are acceptable. If polarized capacitors are used, connect polarity as shown in the *Typical Operating Circuit*.

Bypass VCC and V- to ground with at least 0.1µF.

Transmitter Outputs When Exiting Shutdown

Figure 1 shows the transmitter output when exiting shutdown mode. The transmitter is loaded with $3k\Omega$ in

parallel with 1000pF. The transmitter output displays no ringing or undesirable transients as the MAX3314E comes out of shutdown.

High Data Rates

The MAX3314E maintains minimum RS-232-compatible ±3.7V transmitter output voltage even at high data rates. Figure 2 shows a transmitter loopback test circuit. Figure 3 shows the loopback test result at 120kbps, and Figure 4 shows the same test at 250kbps.

±15kV ESD Protection

As with all Maxim devices, ESD-protection structures are incorporated on all pins to protect against electrostatic discharges encountered during handling and assembly. The MAX3314E driver outputs and receiver inputs have extra protection against static discharge. Maxim's engineers have developed state-of-the-art structures to protect these pins against ESD of ±15kV without damage. The ESD structures withstand high ESD in all states: normal operation, shutdown, and powered down. After an ESD event, Maxim's E versions keep working without latchup, whereas competing products can latch and must be powered down to remove latchup.

ESD protection can be tested in various ways. The transmitter outputs and receiver inputs of the product family are characterized for protection to the following limits:

- ±15kV using the Human Body Model
- ±8kV using the Contact Discharge method specified in IEC 1000-4-2
- ±15kV using the IEC 1000-4-2 Air-Gap method

Table 1. Shutdown Logic Truth Table

SHDN	TRANSMITTER OUTPUT	RECEIVER OUTPUT	
L	High Z	Active	
Н	Active	Active	

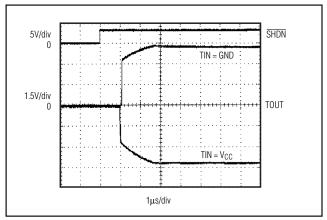


Figure 1. Transmitter Outputs When Exiting Shutdown or Powering Up

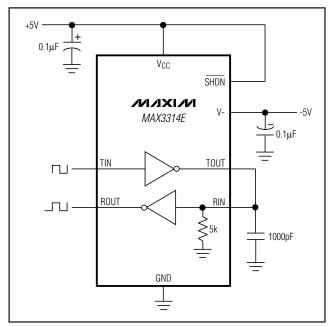


Figure 2. Loopback Test Circuit

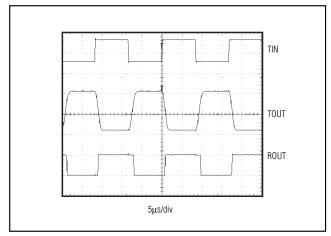


Figure 3. Loopback Test Result at 120kbps

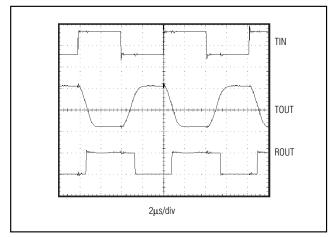


Figure 4. Loopback Test Result at 250kbps

ESD Test Conditions

ESD performance depends on a variety of conditions. Contact Maxim for a reliability report that documents test setup, test methodology, and test results.

Human Body Model

Figure 5 shows the Human Body Model, and Figure 6 shows the current waveform it generates when discharged into low impedance. This model consists of a 100pF capacitor charged to the ESD voltage of interest, which is then discharged into the test device through a $1.5 \mathrm{k}\Omega$ resistor.

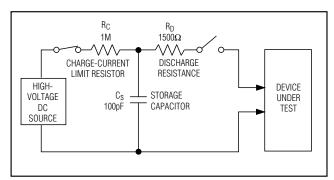


Figure 5. Human Body ESD Test Model

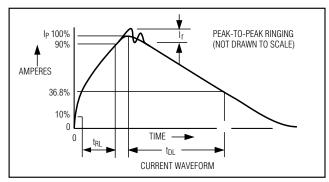


Figure 6. Human Body Current Waveform

IEC 1000-4-2

The IEC 1000-4-2 standard covers ESD testing and performance of finished equipment; it does not specifically refer to ICs. The MAX3314E helps design equipment that meets Level 4 (the highest level) of IEC 1000-4-2 without the need for additional ESD-protection components

The major difference between tests done using the Human Body Model and IEC 1000-4-2 is higher peak current in IEC 1000-4-2 because series resistance is lower in the IEC 1000-4-2 model. Hence, the ESD withstand voltage measured to IEC 1000-4-2 is generally lower than that measured using the Human Body Model. Figure 7 shows the IEC 1000-4-2 model, and Figure 8 shows the current waveform for the 8kV, IEC 1000-4-2, Level 4, ESD Contact Discharge test.

The Air-Gap test involves approaching the device with a charged probe. The Contact Discharge method connects the probe to the device before the probe is energized.

Machine Model

The Machine Model for ESD tests all pins using a 200pF storage capacitor and zero discharge resistance. Its objective is to emulate the stress caused by

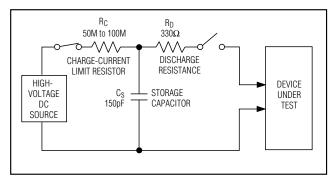


Figure 7. IEC 1000-4-2 ESD Test Model

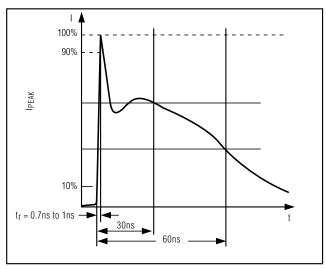


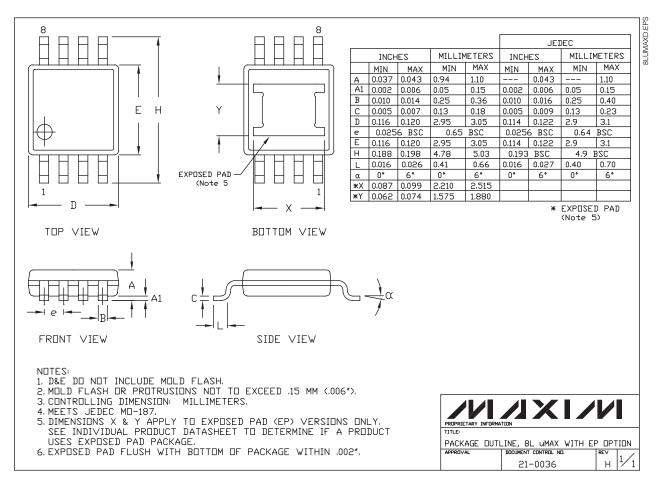
Figure 8. IEC 1000-4-2 ESD Generator Current Waveform

contact that occurs with handling and assembly during manufacturing. Of course, all pins require this protection during manufacturing, not just RS-232 inputs and outputs. Therefore, after PC board assembly, the Machine Model is less relevant to I/O ports.

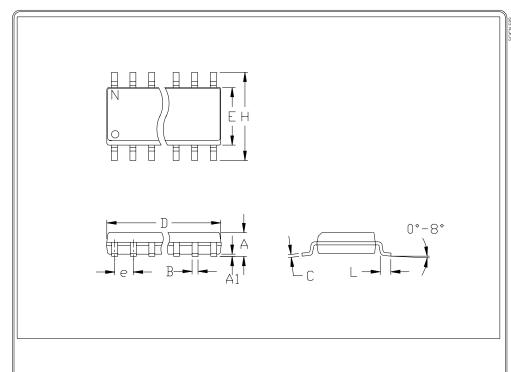
_Chip Information

TRANSISTOR COUNT: 128

Package Information



Package Information (continued)



	INC		HES	MILLIM	<u>IETERS</u>
		MIN	MAX	MIN	MAX
	\triangle	0.053	0.069	1.35	1.75
	Α1	0.004	0.010	0.10	0.25
	B C	0.014	0.019	0.35	0.49
		0.007	0.010	0.19	0.25
	Û	0.0)50	1.7	27
	E	0.150	0.157	3.80	4.00
	Τ	0.228	0.244	5.80	6.20
	7	0.010	0.020	0.25	0.50
	Ĺ	0.016	0.050	0.40	1.27

	INCHES		MILLIM			
	MIN MAX		MIN	MAX	Ν	MS012
D	0.189	0.197	4.80	5.00	8	Α
D	0.337	0.344	8.55	8.75	14	В
D	0.386	0.394	9.80	10.00	16	С

NOTES:

- 1. D&E DO NOT INCLUDE MOLD FLASH
 2. MOLD FLASH OR PROTRUSIONS NOT
 TO EXCEED .15mm (.006")
 3. LEADS TO BE COPLANAR WITHIN
 .102mm (.004")

- 4. CONTROLLING DIMENSION: MILLIMETER
 5. MEETS JEDEC MS012-XX AS SHOWN
 IN ABOVE TABLE
 6. N = NUMBER OF PINS

PACKAGE FAMILY DUTLINE: SDIC .150" 21-0041 A

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

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